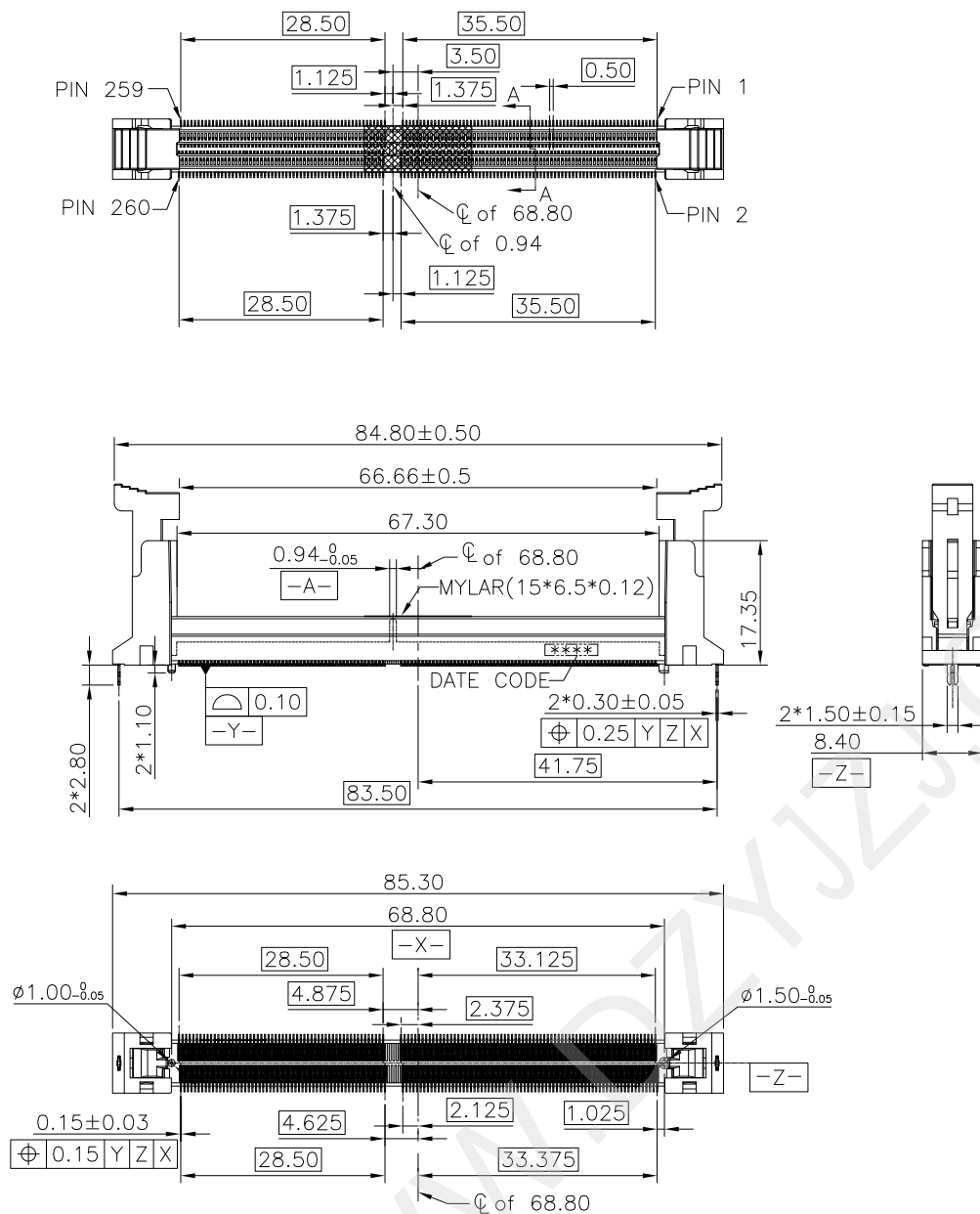




NOTES:

1. MATERIAL SPECIFICATION:

- 1-1. HOUSING: LCP+40%GF,UL94V-0,COLOR: BLACK.
1-2. CONTACTS:COPPER_C7025,T=0.15mm;
1-3. HOOK: BRASS_C2680,T=0.30mm;
1-4. EJECTOR: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, COLOR: BLACK.
1-5. MYLAR: INSULATOR MATERIAL, COLOR: BROWN;

2. PLATING SPECIFICATION:

- 2-1. CONTACT: NICKEL 50u" MIN. UNDER PLATING OVER ALL.MATTE TIN 100u" MIN. PLATING ON SOLDER AREA.GOLD PLATING SEE TABLE1.
2-2. HOOK: NICKEL 50u" MIN. UNDER PLATING OVER ALL. MATTE TIN 100u" MIN. PLATING OVER ALL.

3. RoHS OR HF COMPLIANT;

4. DATE CODE: ****
WEEK
YEAR

5.MECHANICAL PERFORMANCE:

- 5-1. MATING FORCE: 11Kgf MAX..
5-2. DURABILITY: 25 CYCLES.

6. ELECTRICAL PERFORMANCE:

- 6-1. CURRENT: 0.50A MAX. PER PIN.
6-2. VOLTAGE: 25V AC MAX..
6-3. LLCR: 55mΩ MAX. (INITIAL); Δ20mΩ MAX. (FINAL).
6-4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC FOR 1 MINUTE.
6-5. INSULATION RESISTANCE: DC 500V 500MΩ.

7. RECOMMENDED PROCESS;

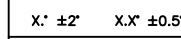
THE TEMPERATURE SHALL BE 260°C MAINTAINING 10 SECONDS.



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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15
X' ±2" X.X' ±0.5'



UNIT: mm [inch]
SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

SODDR4 立贴

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC22-DDR4-254

APPROVED BY:

邱敏

DATE :

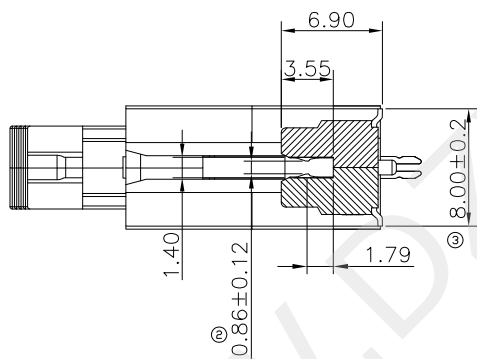
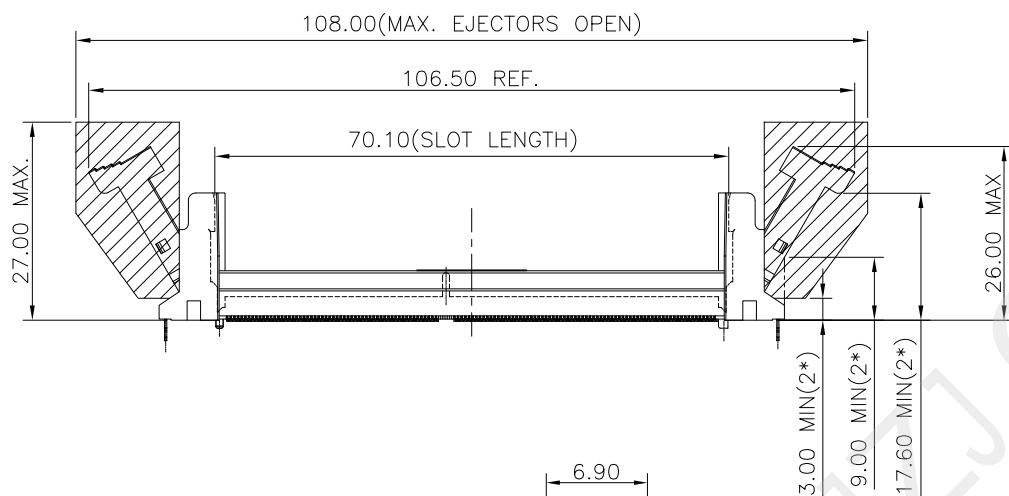
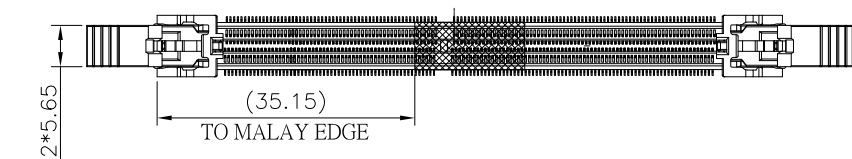
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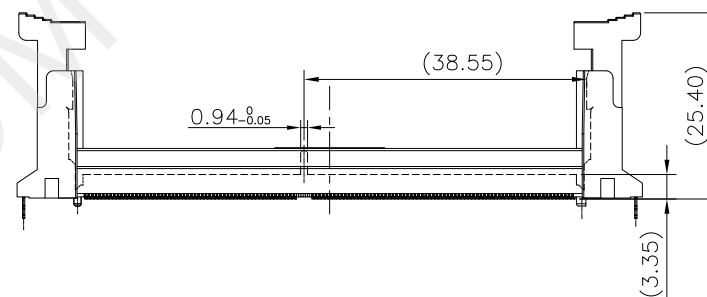
HYC-2302271601

SHEET NO.

1 OF 1



SECTION A-A
SCALE 2:1



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X' ±2° X.X' ±0.5°



UNIT: mm [inch]

SCALE:1:1

SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

SODDR4 立贴

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC22-DDR4-254

MOLD NO.

APPROVED BY:

邱敏

DATE :

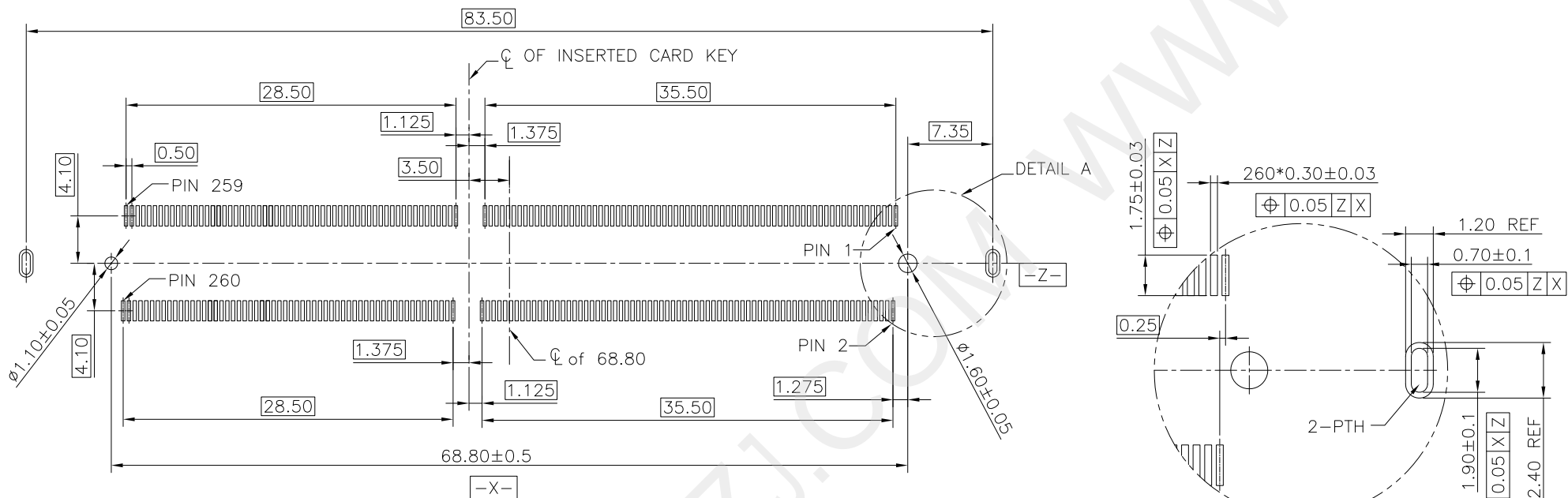
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DRAW NO:

HYC-2302271601

SHEET NO.

1 OF 1



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X.' $\pm 2'$ X.X' $\pm 0.5'$ 

UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY:

陈一鸣

DATE:

2014-02-23

CHECKED BY:

马跃

DATE:

2014-02-23

APPROVED BY:

邱敏

DATE:

2014-02-23

PART NAME:

SODDR4 立贴

PART NO.

HYC22-DDR4-254

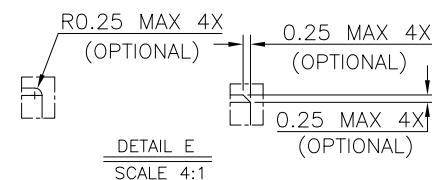
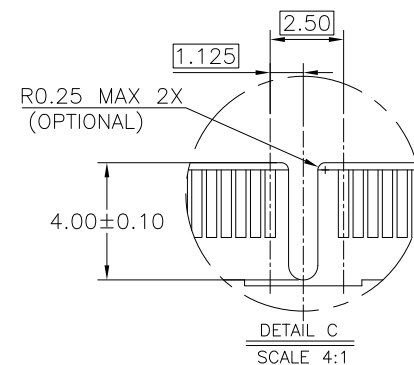
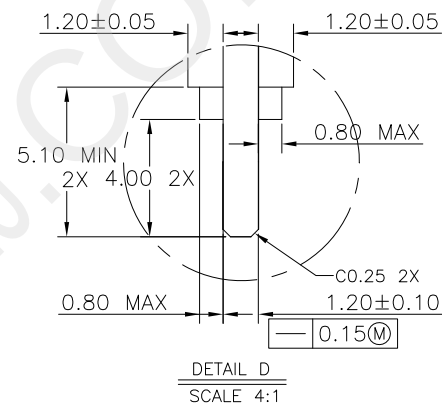
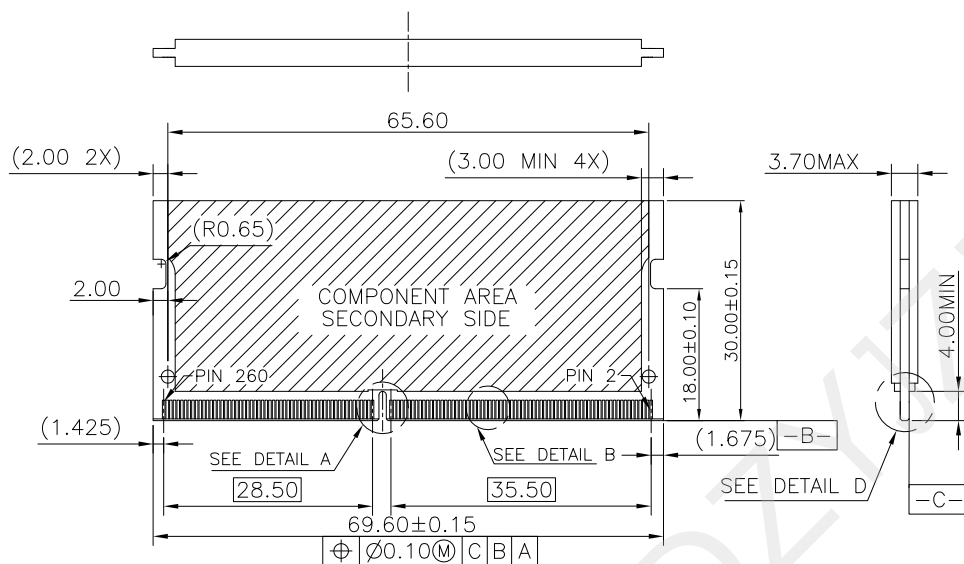
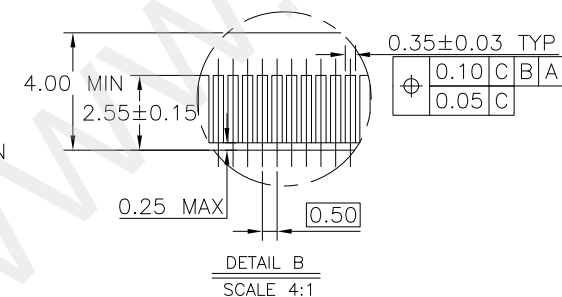
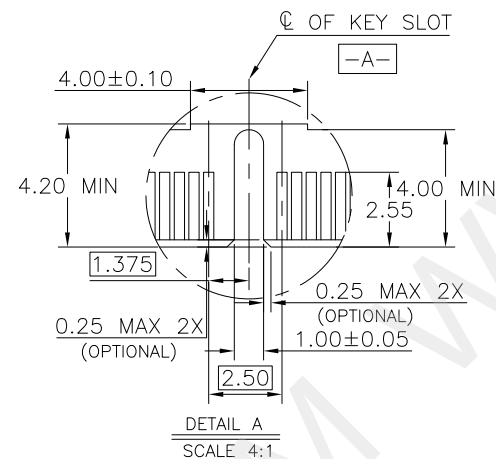
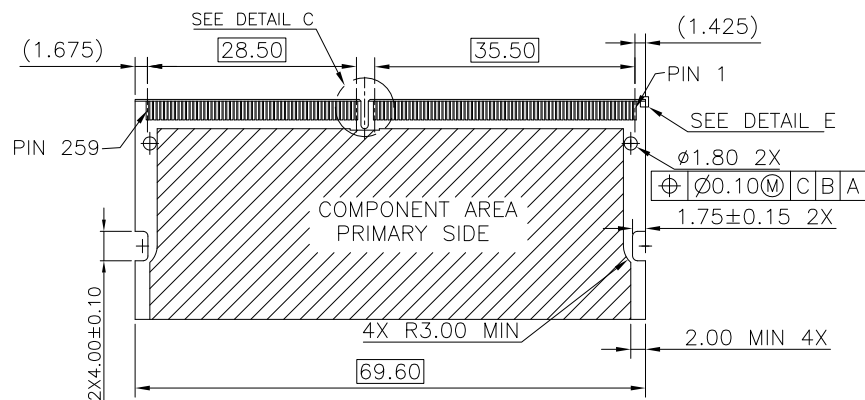
MOLD NO.

DRAW NO:

HYC-2302271601

SHEET NO.

1 OF 1



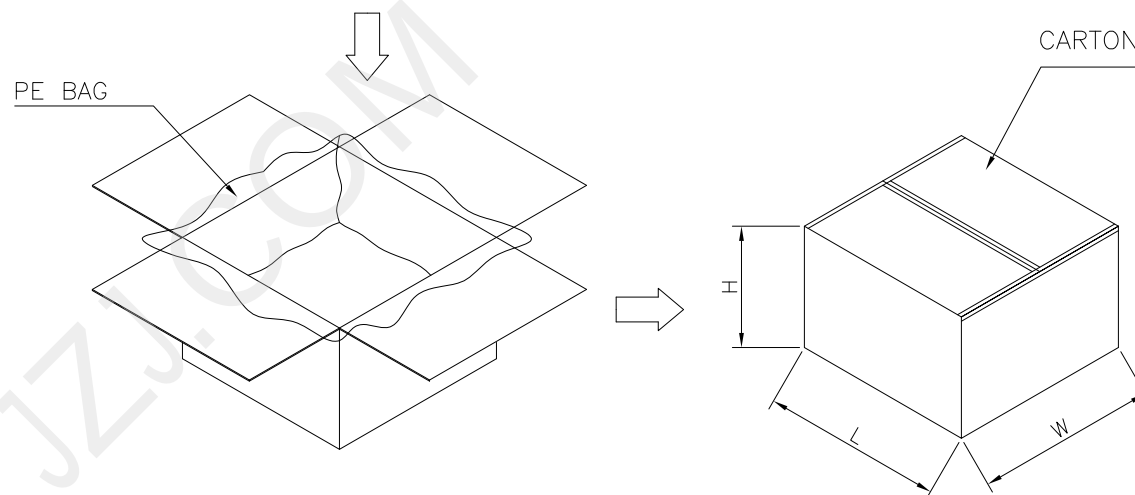
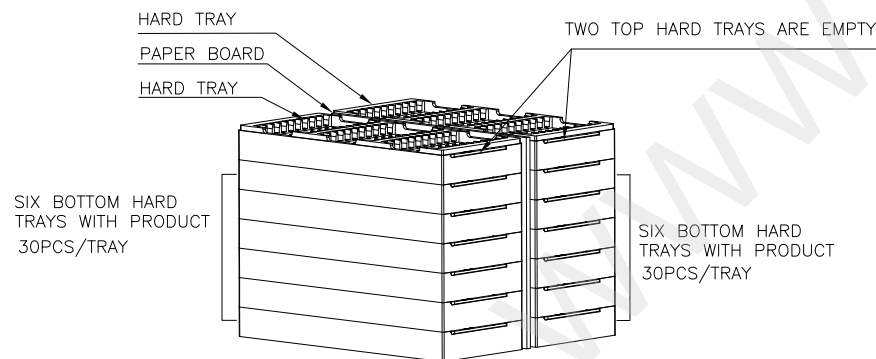
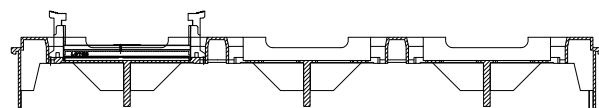
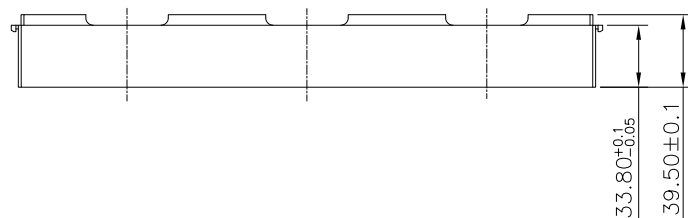
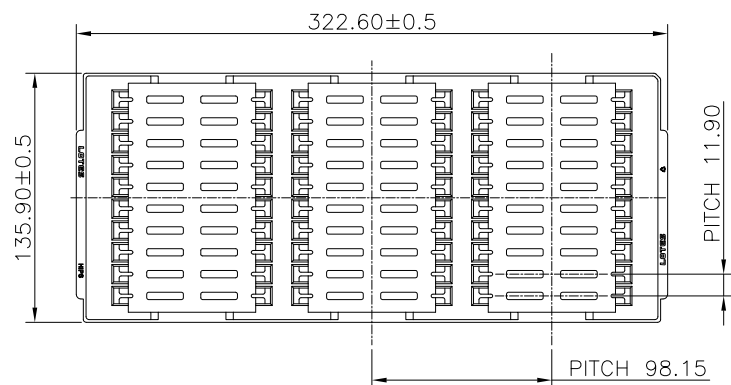
MATING P.C.B NOTES:

1. TOLERANCE ON ALL DIMENSIONS ± 0.05 UNLESS OTHERWISE SPECIFIED;
2. PCB THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION;
3. FINISH OF PAD: Au PLATING 30u"min OVER Ni PLATING 80u" MIN.;
4. NO BURR.
5. CHAMFER 0.25mm max. X 45° IF EXIST.



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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SODDR4 立贴
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC22-DDR4-254
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2302271601
			SHEET NO. 1 OF 1



5	PE BAG	400*350*350 T=0.04	1 PCS
4	CARTON	285*325*255;K=A	1 PCS
3	PAPER BOARD	300*270*6	3 PCS
2	HARD TRAY	322.6*135.9*39.50;HIPS_BLACK	14 PCS
1	CONNECTOR	SEE TABLE 1	360 PCS
NO.	DESCRIPTION	SPECIFICATION	QT'Y



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X" ±0.5" UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 包装图	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	
	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO:	
			SHEET NO.	1 OF 1